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AT24C128 Ordering Information⁽¹⁾

Ordering Code	Package	Operation Range
AT24C128-10PI-2.7	8P3	Industrial Temperature (–40°C to 85°C)
AT24C128N-10SI-2.7	8S1	
AT24C128W-10SI-2.7	8S2	
AT24C128-10TI-2.7	8A2	
AT24C128-10PI-1.8	8P3	Industrial Temperature (–40°C to 85°C)
AT24C128N-10SI-1.8	8S1	
AT24C128W-10SI-1.8	8S2	
AT24C128-10TI-1.8	8A2	
AT24C128-10PU-2.7 ⁽²⁾	8P3	Lead-free/Halogen-free/ Industrial Temperature (–40°C to 85°C)
AT24C128-10PU-1.8 ⁽²⁾	8P3	
AT24C128N-10SU-2.7 ⁽²⁾	8S1	
AT24C128N-10SU-1.8 ⁽²⁾	8S1	
AT24C128-10TU-2.7 ⁽²⁾	8A2	
AT24C128-10TU-1.8 ⁽²⁾	8A2	
AT24C128U2-10UU-1.8 ⁽²⁾	8U2-1	
AT24C128Y1-10YU-1.8 ⁽²⁾	8Y1	
AT24C128Y4-10YU-1.8 ⁽²⁾	8Y4	
AT24C128-W2.7-11 ⁽³⁾	Die Sale	Industrial Temperature (–40°C to 85°C)
AT24C128-W1.8-11 ⁽³⁾	Die Sale	

Notes: 1. For 2.7V devices used in the 4.5V to 5.5V range, please refer to performance values in the AC and DC characteristics tables.
2. “U” and “Q” designates Green package + RoHS compliant
3. Available in waffle pack and wafer form; order as SL719 for wafer form. Bumped die available upon request. Please contact Serial EEPROM Marketing.

Package Type	
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC)
8S2	8-lead, 0.200" Wide, Plastic Gull Wing Small Outline Package (EIAJ SOIC)
8U2-1	8-ball, die Ball Grid Array Package (dBG2)
8Y1	8-lead, 4.90 mm x 3.00 mm Body, Dual Footprint, Non-leaded, Miniature Array Package (MAP)
8Y4	8-lead, 6.00 mm x 4.90 mm Body, Dual Footprint, Non-leaded, Small Array Package (SAP)
8A2	8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)
Options	
–2.7	Low-voltage (2.7V to 5.5V)
–1.8	Low-voltage (1.8V to 3.6V)

AT24C256 Ordering Information⁽¹⁾

Ordering Code	Package	Operation Range
AT24C256-10PI-2.7 AT24C256N-10SI-2.7 AT24C256W-10SI-2.7 AT24C256-10TI-2.7	8P3 8S1 8S2 8A2	Industrial Temperature (–40°C to 85°C)
AT24C256-10PI-1.8 AT24C256N-10SI-1.8 AT24C256W-10SI-1.8 AT24C256-10TI-1.8	8P3 8S1 8S2 8A2	Industrial Temperature (–40°C to 85°C)
AT24C256-10PU-2.7 ⁽²⁾ AT24C256-10PU-1.8 ⁽²⁾ AT24C256N-10SU-2.7 ⁽²⁾ AT24C256N-10SU-1.8 ⁽²⁾ AT24C256-10TU-2.7 ⁽²⁾ AT24C256-10TU-1.8 ⁽²⁾ AT24C256U2-10UU-1.8 ⁽²⁾ AT24C256Y4-10YU-1.8 ⁽²⁾	8P3 8P3 8S1 8S1 8A2 8A2 8U2-1 8Y4	Lead-free/Halogen-free/ Industrial Temperature (–40°C to 85°C)
AT24C256-W2.7-11 ⁽³⁾ AT24C256-W1.8-11 ⁽³⁾	Die Sale Die Sale	Industrial Temperature (–40°C to 85°C)

Notes: 1. For 2.7V devices used in the 4.5V to 5.5V range, please refer to performance values in the AC and DC characteristics tables.
2. “U” and “Q” designates Green Package + RoHS compliant
3. Available in waffle pack and wafer form; order as SL719 for wafer form. Bumped die available upon request. Please contact Serial EEPROM Marketing.

Package Type	
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC)
8S2	8-lead, 0.200" Wide, Plastic Gull Wing Small Outline Package (EIAJ SOIC)
8U2-1	8-ball, die Ball Grid Array Package (dBGAA2)
8Y4	8-lead, 6.00 mm x 4.90 mm Body, Dual Footprint, Non-leaded, Small Array Package (SAP)
8A2	8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)
Options	
–2.7	Low-voltage (2.7V to 5.5V)
–1.8	Low-voltage (1.8V to 3.6V)